



## Material Content Data Sheet



<b>Sales Product Name</b>		IDP45E60		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000734808							
<b>Package</b>		PG-TO220-2-1		<b>Weight*</b>		1964.24 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.355	0.12	0.12	1199	1199	
leadframe	inorganic material	phosphorus	7723-14-0	0.403	0.02		205		
	non noble metal	iron	7439-89-6	1.343	0.07		684		
	non noble metal	copper	7440-50-8	1341.263	68.29	68.38	682841	683729	
	non noble metal	aluminium	7429-90-5	5.480	0.28	0.28	2790	2790	
wire	non noble metal	aluminium	7429-90-5	5.480	0.28	0.28	2790	2790	
encapsulation	organic material	carbon black	1333-86-4	5.980	0.30		3044		
	plastics	epoxy resin	-	113.611	5.78		57839		
	inorganic material	silicondioxide	60676-86-0	478.360	24.35	30.43	243534	304418	
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7375	7375	
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101	
solder	non noble metal	antimony	7440-36-0	0.076	0.00		39		
	noble metal	silver	7440-22-4	0.190	0.01		97		
	non noble metal	tin	7440-31-5	0.495	0.03	0.04	252	388	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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